# Monthly LabAdviser update: 12/3 2018

|  |  |  |
| --- | --- | --- |
| Updated Subject  | Contributor | Link to the updated pages |
| **LPCVD nitride**Stress measurements of LPCVD nitride films | **Martin Lind Ommen @Nanotech** | [LPCVD\_nitride\_furnace#Stress\_measurements](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_Nitride/Deposition_of_stoichiometric_nitride_using_the_4%22_LPCVD_nitride_furnace#Stress_measurements)[Deposition\_of\_low\_stress\_nitride\_using\_the\_6%22\_LPCVD\_nitride\_furnace](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_Nitride/Deposition_of_low_stress_nitride_using_the_6%22_LPCVD_nitride_furnace) |
| **PECVD – conformity**SEM images of the conformity of PECVD glass from PECVD4 | **Lasse H. Thamdrup @NILT** | [PECVD/conformity#SiO2\_deposition\_on\_holes\_with\_diameter\_431nm-442nm\_nad\_depth\_257\_nm](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Deposition_of_Silicon_Oxide_using_PECVD/conformity#SiO2_deposition_on_holes_with_diameter_431nm-442nm_nad_depth_257_nm) |
| **RCA**Process description and background information updated | **Claus H. Nielsen @danchip** | [Wafer\_cleaning/RCA](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Wafer_cleaning/RCA) |
| **Polymer Injection Molder**General update and new section describing the most important injection molding machine parameters. | **Claus H. Nielsen @danchip** | [Polymer\_Injection\_Molder](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Polymer_Injection_Molder) |
| **Hardness measurement (new page)**New page describing capabilities of the Vickers hardness tester available in the cleanroom | **Claus H. Nielsen @danchip** | [Hardness\_measurement](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Hardness_measurement) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

|  |  |  |
| --- | --- | --- |
|

|  |
| --- |
| 5. 3. 6.01) Manual for Flip Chip bonder, ver 45. 3. 1.12) Manual for MVD, ver 45. 3. 6.12) Manual for Ball wire-bonder, ver 2.15. 3. 3.05) Manual for ASE, ver 25. 3. 7.07) Manual for Drop Shape Analyzer, ver 25. 3. 2.08) Manual for PECVD3, ver 1.6 5. 3. 1.10) Manual for KS Aligner\_ MA6, ver 65. 3. 1.17) Manual for DUV Stepper., ver 35. 3. 1.30) Manual for SÜSS Spinner-Stepper., ver 35. 3. 1.38) Manual for Hotplate: 90-110C, ver 2 5. 3. 6.04) Manual for Polisher/Lapper, ver 1.25. 3. 6.14) Manual for Vacuum Sealer, ver 5. 3. 7.51) Manual for Hardness tester, ver 15. 3. 6.16) Manual for Polymer Dryer 1 and 2, ver 1.15. 3. 1.44) Manual for Spin Coater: Gamma UV, ver 1.15. 3. 1.21) Manual for Oven 250C, ver 1.2 |

 |  |